Ankit Kaul

List of Publications by Year
in descending order

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11 papers	49 citations	2258059 3 h-index	2272923 4 g-index
12 all docs	12 docs citations	12 times ranked	22 citing authors

#	Article	IF	Citations
1	A Compute-in-Memory Hardware Accelerator Design With Back-End-of-Line (BEOL) Transistor Based Reconfigurable Interconnect. IEEE Journal on Emerging and Selected Topics in Circuits and Systems, 2022, 12, 445-457.	3.6	5
2	Multilevel Signaling for High-Speed Chiplet-to-Chiplet Communication. IFIP Advances in Information and Communication Technology, 2021, , 149-178.	0.7	1
3	Monolithic Microfluidic Cooling of a Heterogeneous 2.5-D FPGA With Low-Profile 3-D Printed Manifolds. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 974-982.	2.5	6
4	Design Considerations, Demonstration, and Benchmarking of Silicon Microcold Plate and Monolithic Microfluidic Cooling for 2.5D ICs. , 2021, , .		3
5	Thermal Reliability Considerations of Resistive Synaptic Devices for 3D CIM System Performance. , 2021, , .		4
6	Electrical and Performance Benefits of Advanced Monolithic Cooling for 2.5D Heterogeneous ICs. , 2021, , .		0
7	BEOL-Embedded 3D Polylithic Integration: Thermal and Interconnection Considerations. , 2020, , .		12
8	Thermal Modeling of 3D Polylithic Integration and Implications on BEOL RRAM Performance. , 2020, , .		4
9	Benchmarking Monolithic 3D Integration for Compute-in-Memory Accelerators: Overcoming ADC Bottlenecks and Maintaining Scalability to 7nm or Beyond. , 2020, , .		6
10	Microfluidic Cooling of a 14-nm 2.5-D FPGA With 3-D Printed Manifolds for High-Density Computing: Design Considerations, Fabrication, and Electrical Characterization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2393-2403.	2.5	8
11	Modeling and simulation of an HVAC system for energy analysis and management of commercial buildings. , 2014, , .		0